

Photon Meadow conference
Camarda Massimo, SenSiC GmbH
*“Silicon Carbide ultra-thin membranes for X-ray
beam position and intensity monitoring”*



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Outline



- Consideration on solid-state sensors for inline photon diagnostic
- Comparisons on solid state sensors materials
- Opportunities offered by Silicon Carbide membranes
- Achievements (for synchrotron beams)
- Results on “First light” at the Swiss Free Electron Laser
- Conclusions

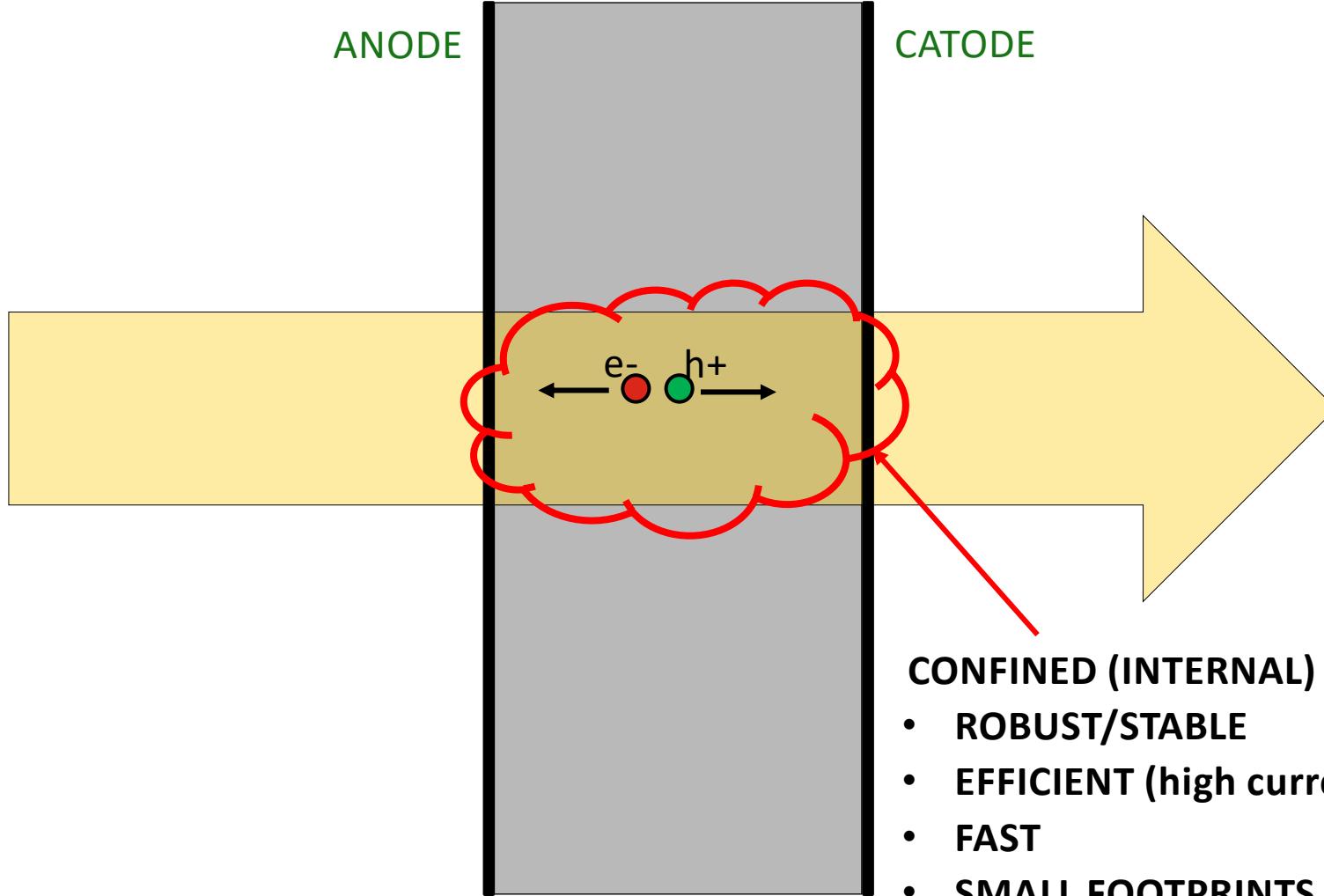


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Considerations on solid-state sensors for inline photon diagnostics



SEN SiC



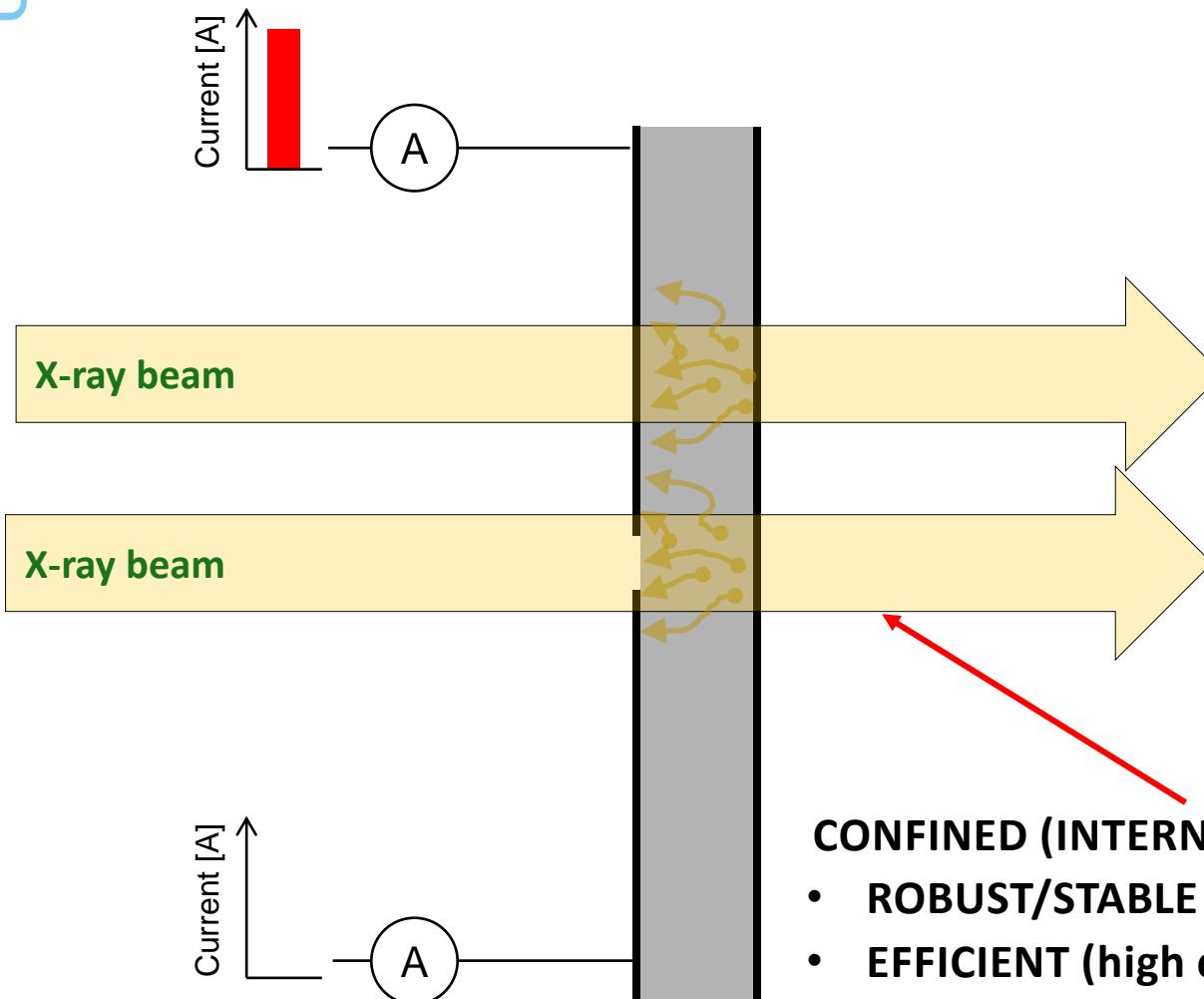
CONFINED (INTERNAL) GENERATION

- ROBUST/STABLE
- EFFICIENT (high currents)
- FAST
- SMALL FOOTPRINTS



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Considerations on solid-state sensors for inline photon diagnostics



CONFINED (INTERNAL) GENERATION

- ROBUST/STABLE
- EFFICIENT (high currents)
- FAST
- SMALL FOOTPRINTS
- **HIGH LATERAL RESOLUTIONS**

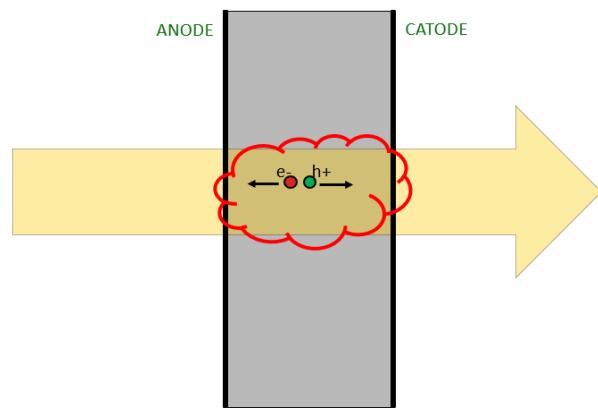


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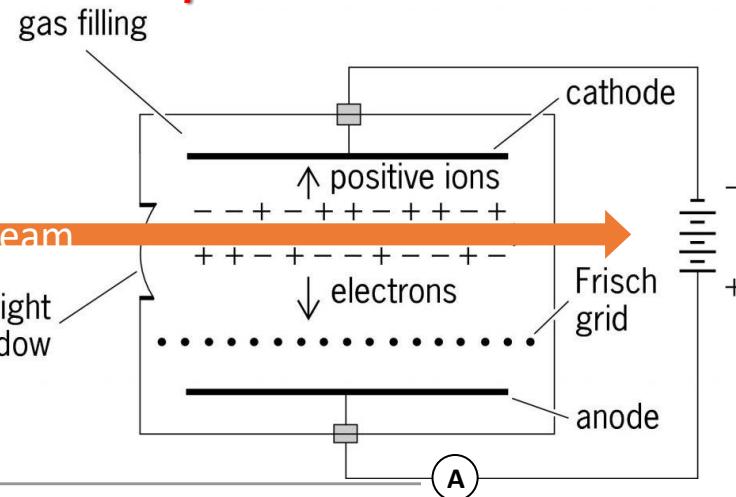
SENSIC
·CH

Comparison of X-ray sensors

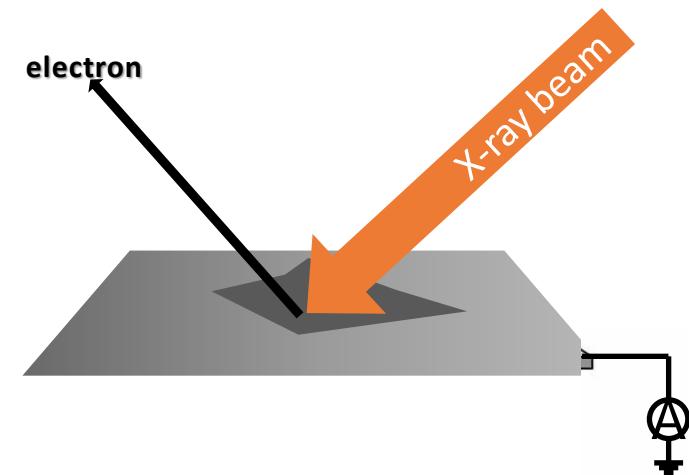
**solid-state based
*internal photoemission***



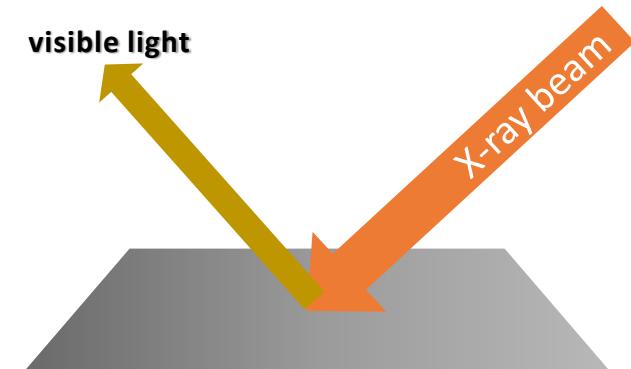
**gas based
*photoionization***



**metal based
*external photoemission***



fluorescence screen

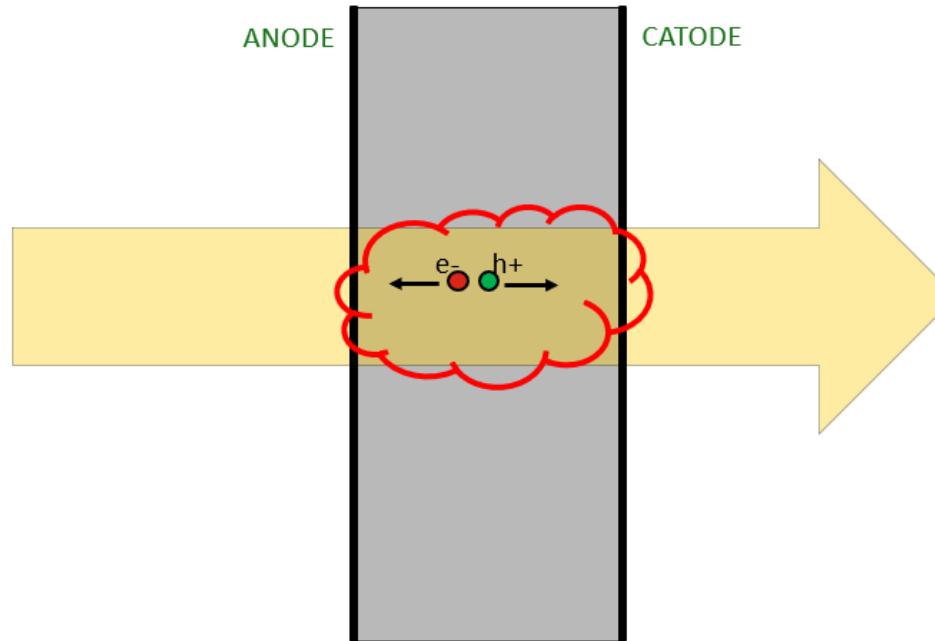




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CH

Considerations on solid-state sensors for photon diagnostics



- CRITICAL ASPECTS** {
- *transparency (>98%)*
 - *stability over time (device degradation)*

Best possible material for solid-state sensors

DIAMOND (CARBON)



Property	Diamond
melting point	4500°C
Thermal conductivity	>1500W/m/K
Xray transparency	high



STL A3

Best possible material for solid-state sensors



DIAMOND (CARBON)



Property	Diamond
material costs	very high
Available crystal size	0.25cm ² (5mmx5mm)
Quality of crystals	“optical” grade
Electron/Hole generation energy	13eV
Doping control	minimal (>1E20cm-3)

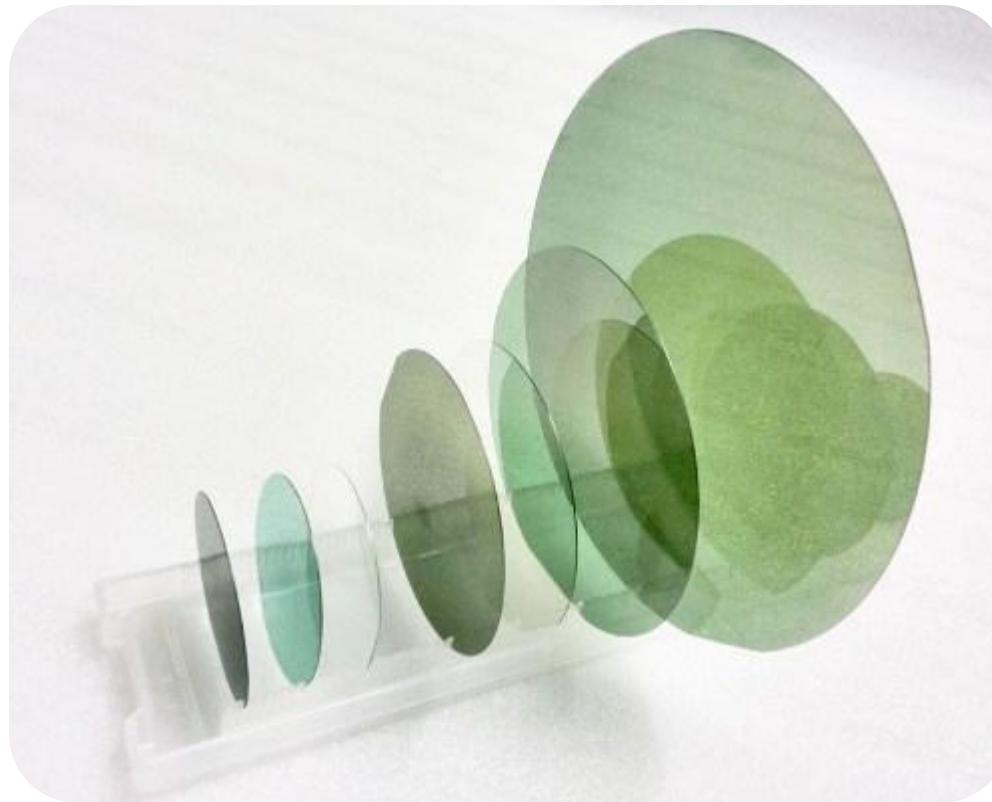


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Best possible material for solid-state sensors

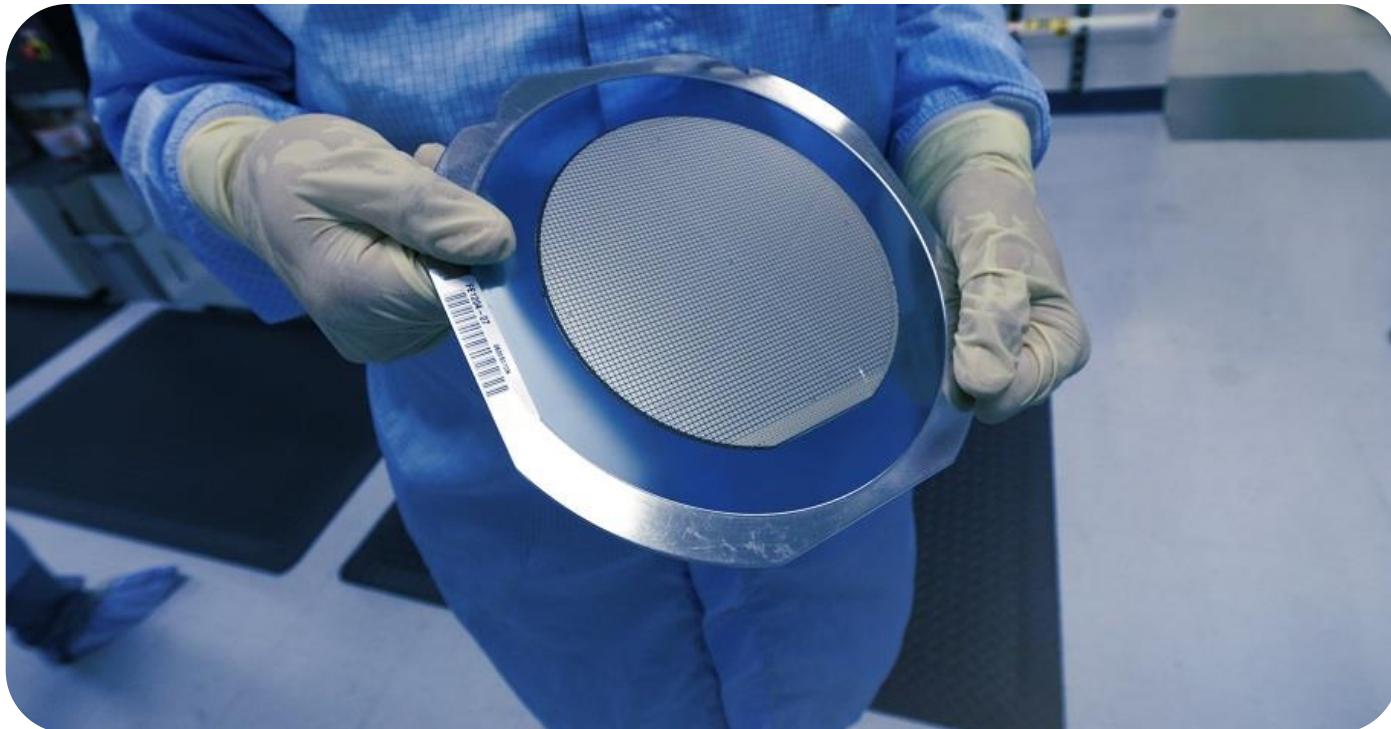


SILICON CARBIDE



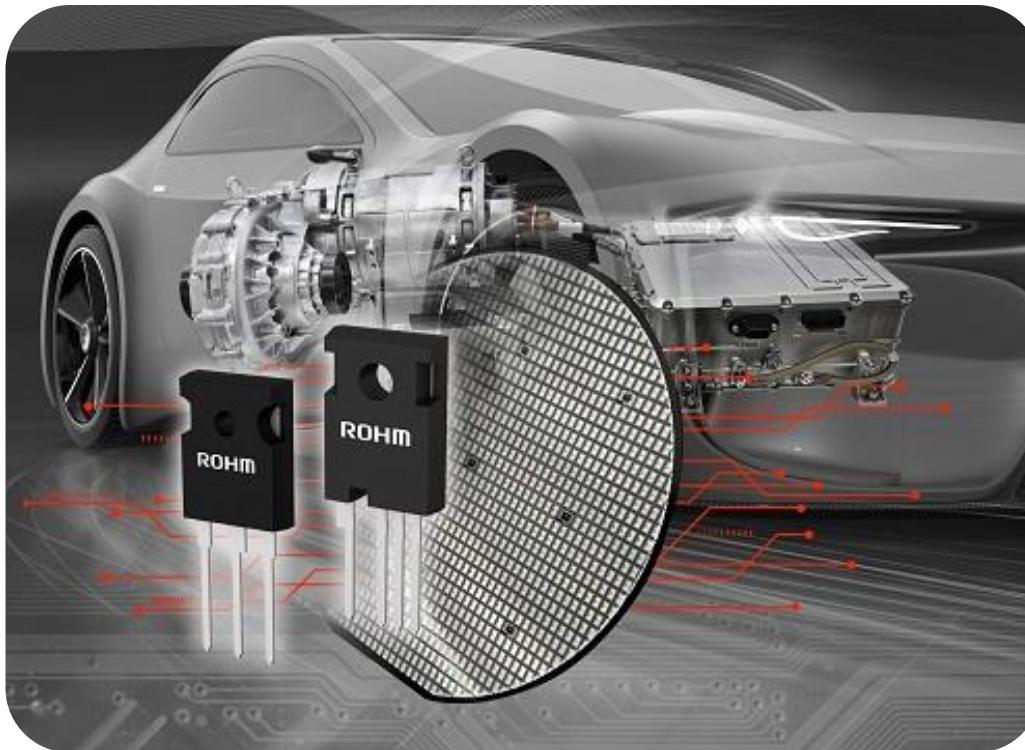
Best possible material for solid-state sensors

SILICON CARBIDE



Best possible material for solid-state sensors

SILICON CARBIDE





Best possible material for solid-state sensors

Property	Diamond	Silicon Carbide
melting point	4500°C	2700°C
Thermal conductivity	>1500W/m/K	400W/m/K
material costs	very high	medium/low
Available crystal size	0.25cm ² (5mmx5mm)	315cm ² (8inch)
Quality of crystals	“optical/electrical” grade	fully industrial
Electron/Hole generation energy	13eV	7.8eV
Doping control	minimal (>1E20cm ⁻³)	high (>5E13cm ⁻³)
Stability of metallisations	low	high

x1260!

Higher signal

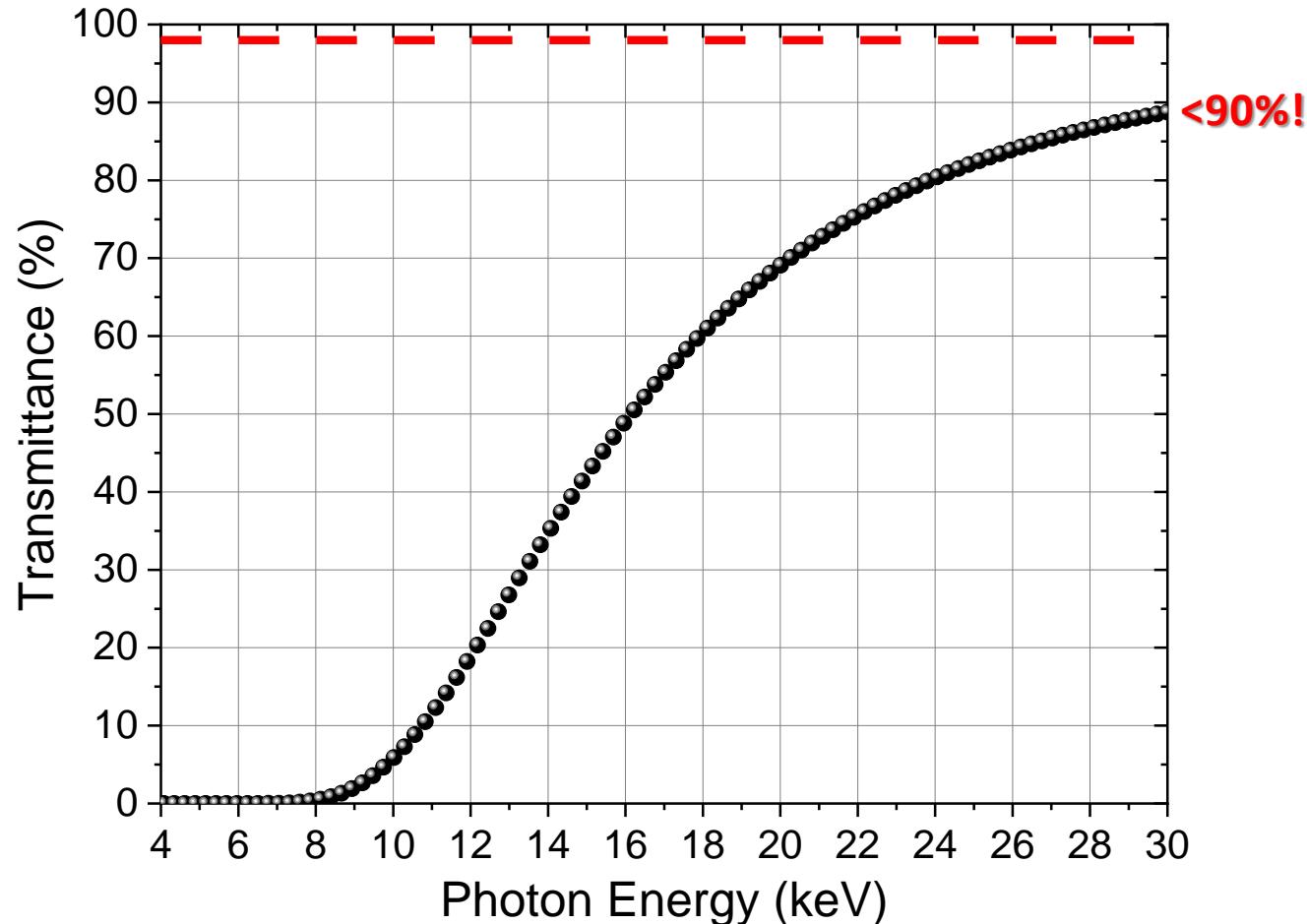
Better sensitivity

Better reliability



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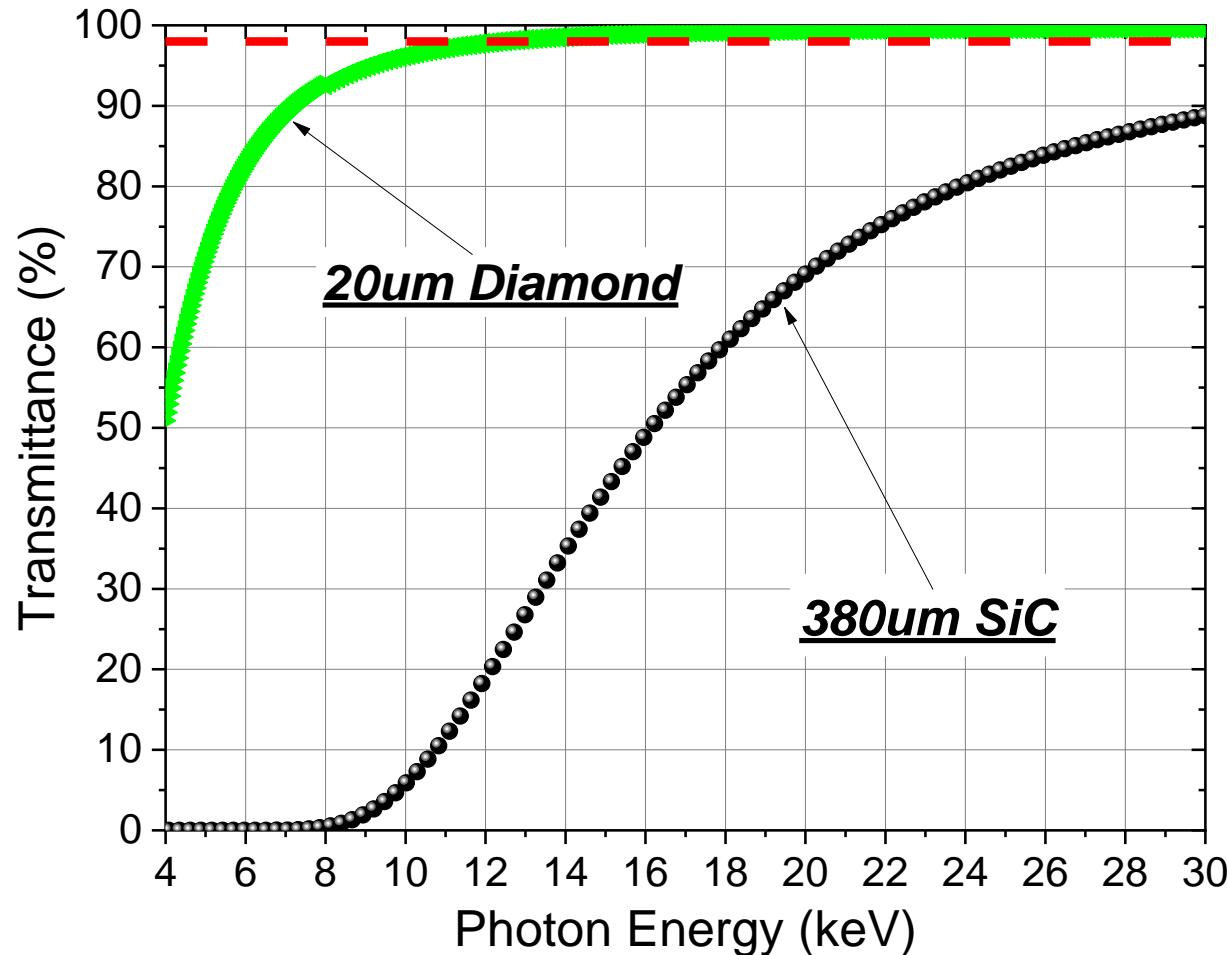
Best possible material for solid-state sensors





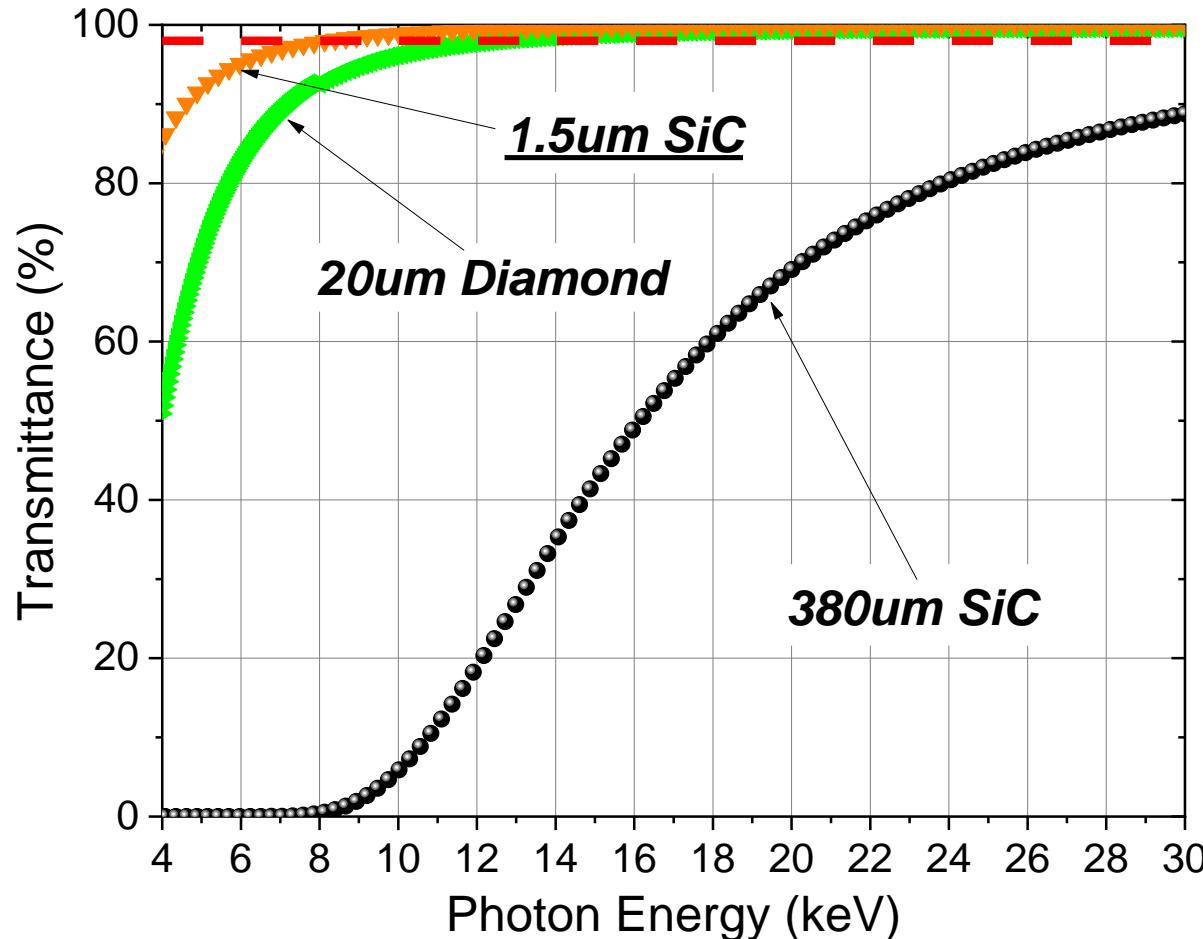
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Best possible material for solid-state sensors



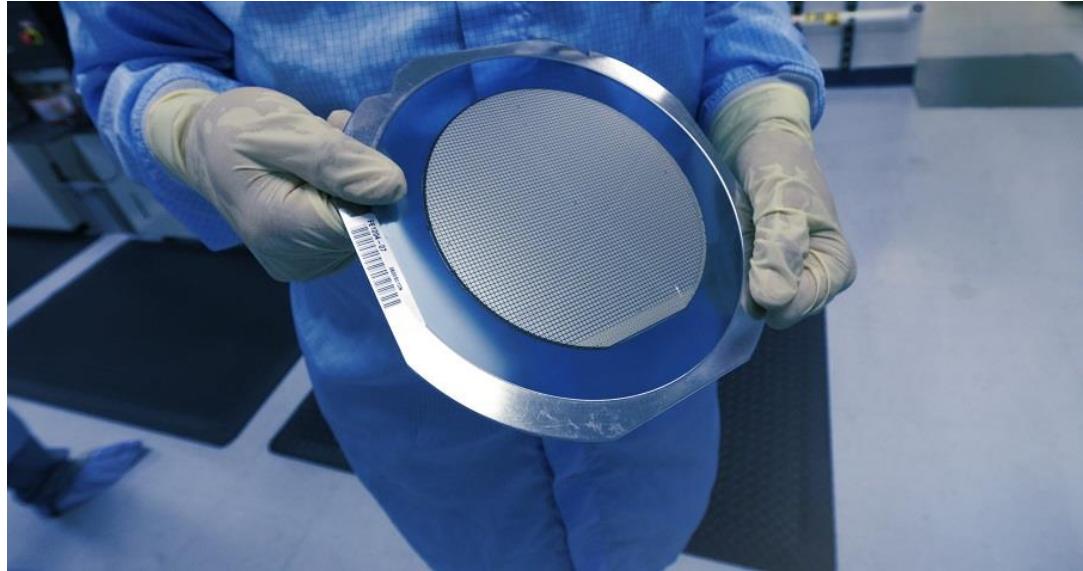


Best possible material for solid-state sensors



Best possible material for solid-state sensors

SILICON CARBIDE



<0.025% etching error needed! (on several mm²)
IMPOSSIBLE TO HANDLE!!



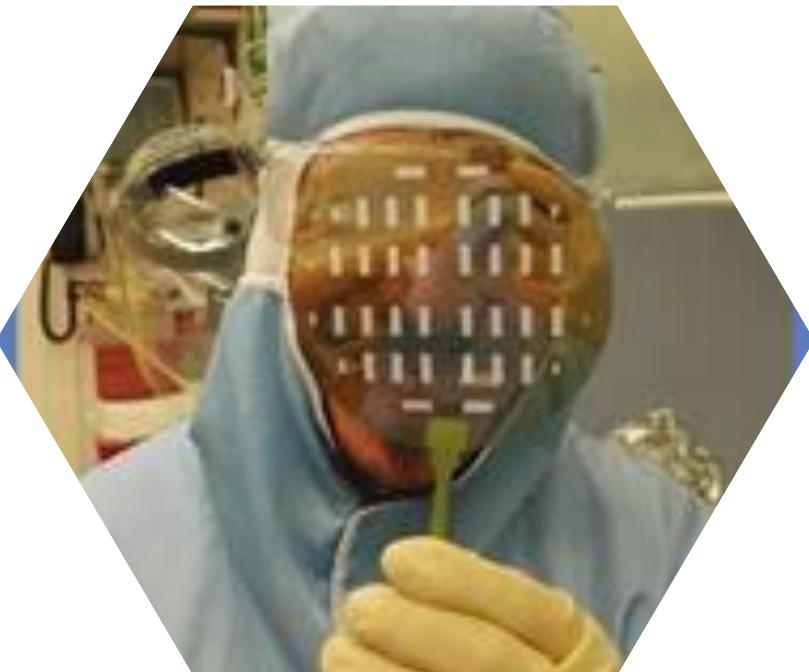
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Best possible material for solid-state sensors



SEnSiC^{CH}

Free-standing
sensors



x.2 Patented thinning
technology
more patents (x2) in
pipeline

>3mm wide

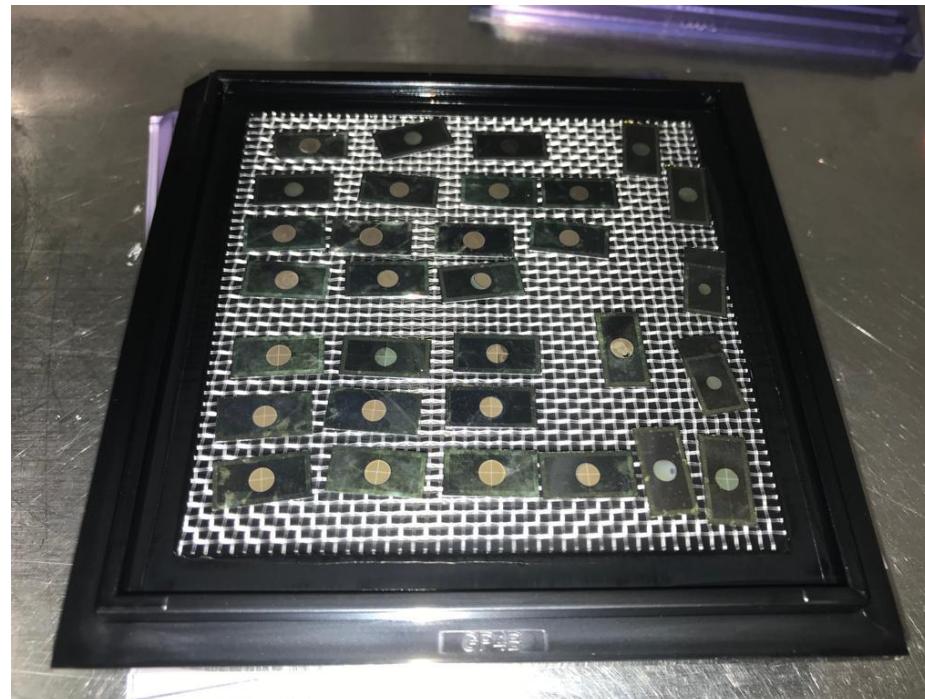
BEAM

<1.5um thickness



Best possible material for solid-state sensors

**SILICON CARBIDE
FREE-STANDING MEMBRANES
INTENSITY AND POSITION MONITORS**

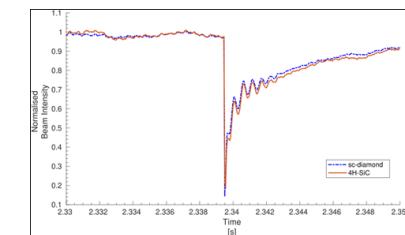
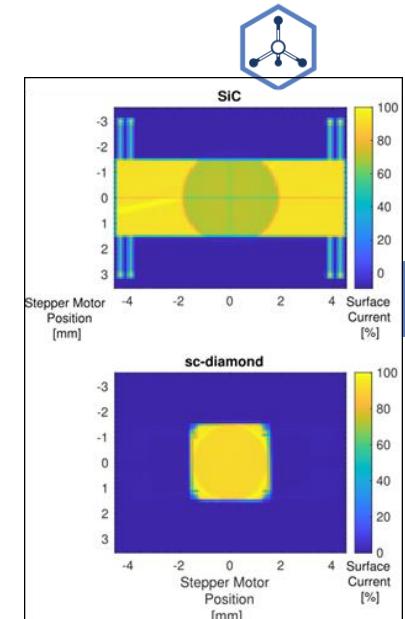
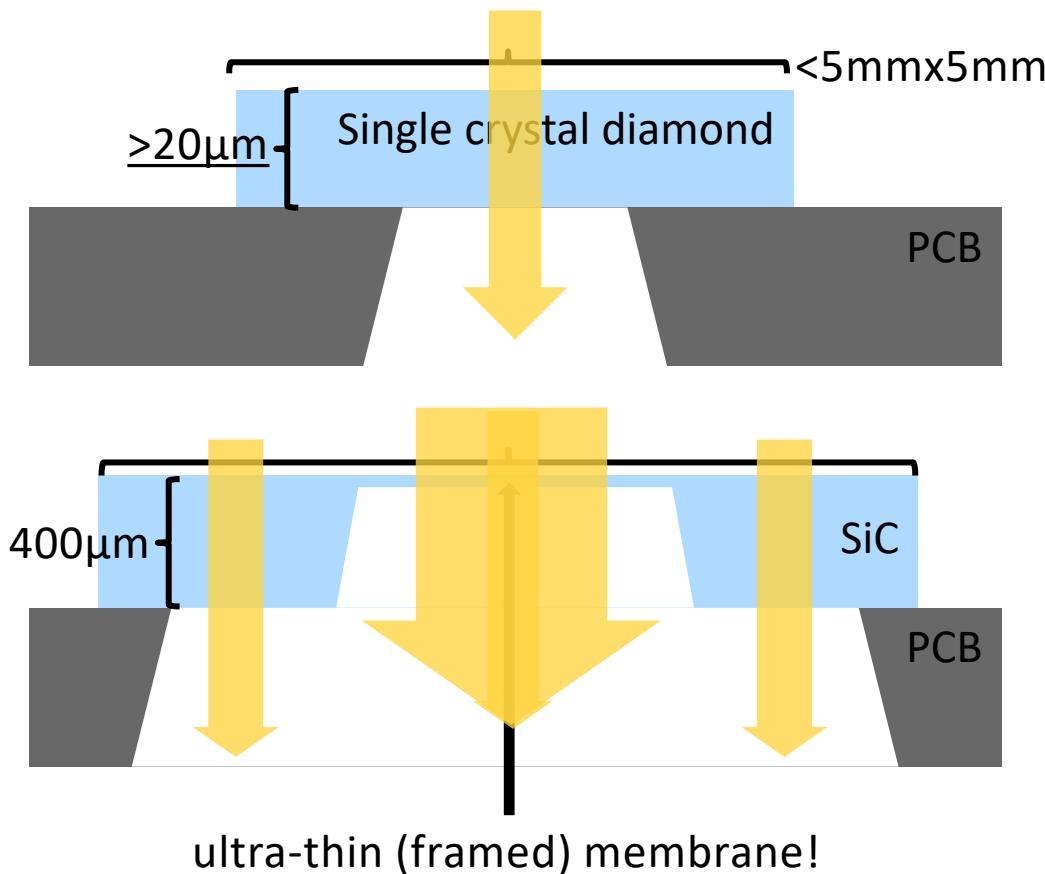




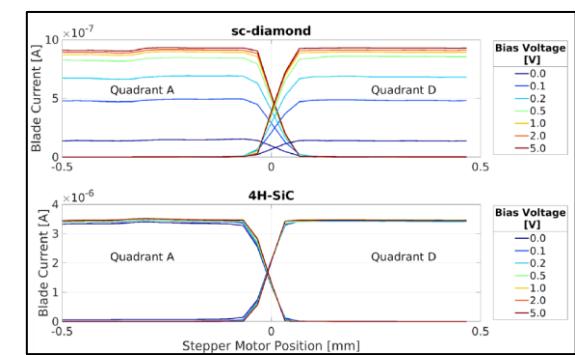
S T L A B

Diamond or Silicon Carbide?

“A direct experimental comparison of single-crystal CVD diamond and silicon carbide X-ray beam position monitors” C. Houghton, JSR 30, 876 (2023)



SenSiC



*up to instrumental limits



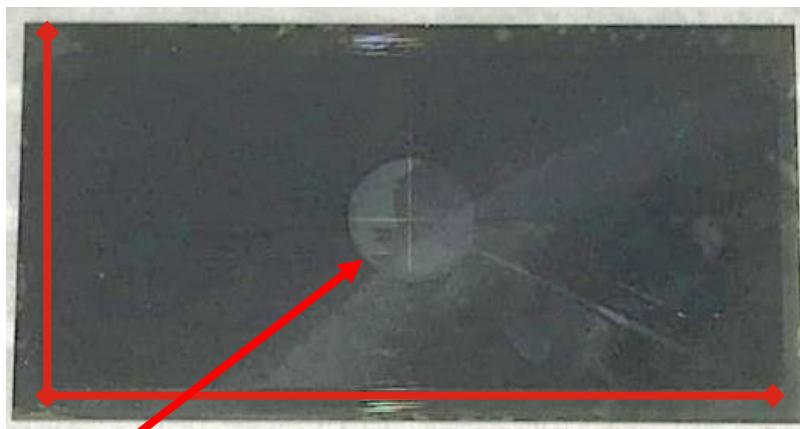
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Best possible material for solid-state sensors

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SILICON CARBIDE

CVD DIAMOND

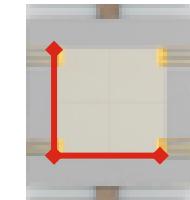


11 mm

23 mm

4 mm Ø

4 mm

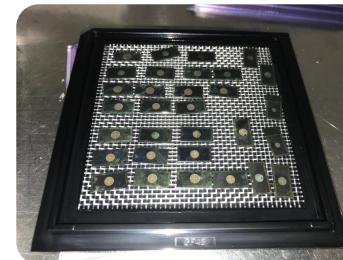
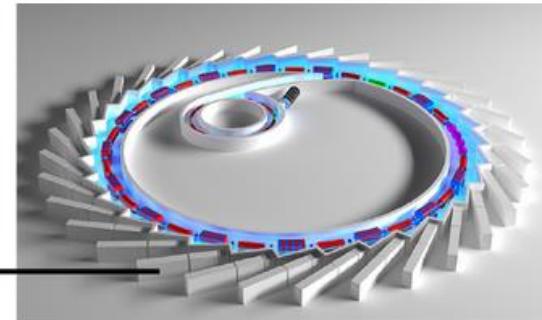
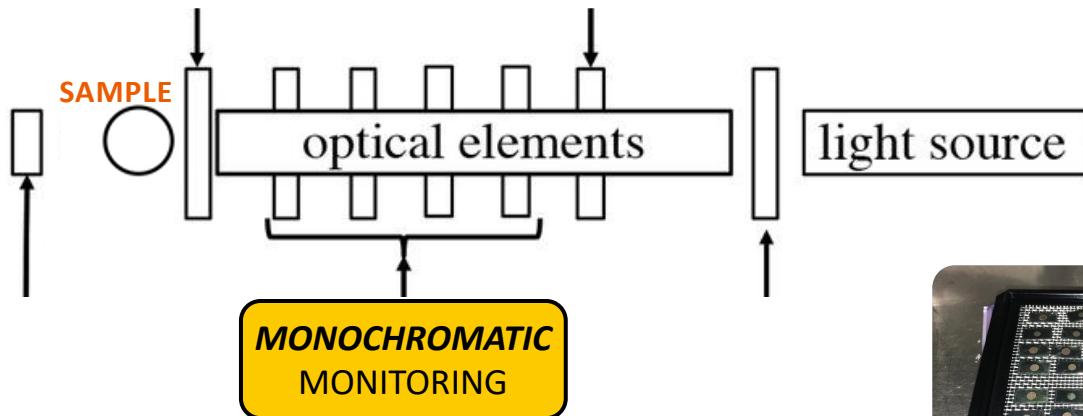


4 mm



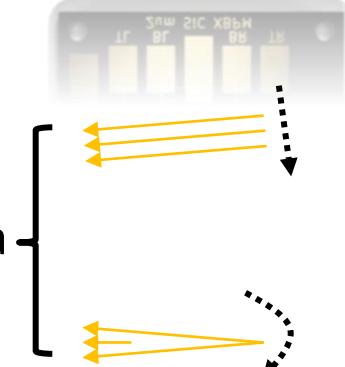
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Locations for in-line Synchrotron monitoring



Commercially available XBPM

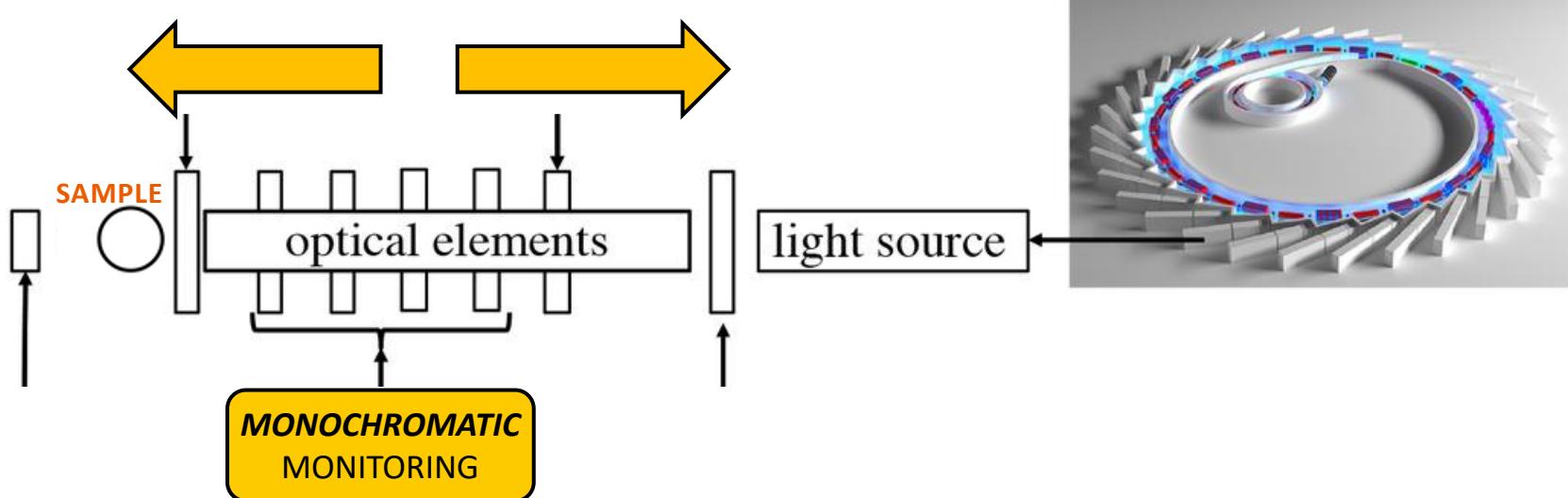
- 1) Monochromatic
- 2) Hard-Xray
- 3) Position
- 4) Only on *single-feedback* schema





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Locations for in-line Synchrotron monitoring

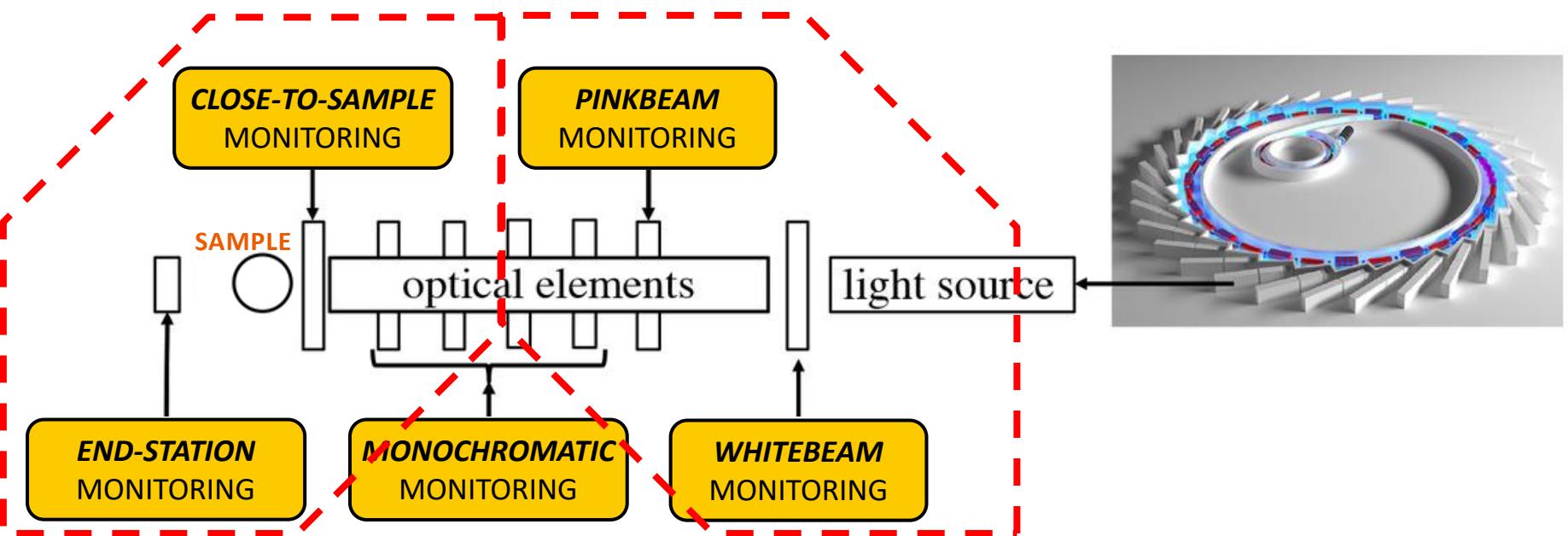




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Locations for in-line Synchrotron monitoring

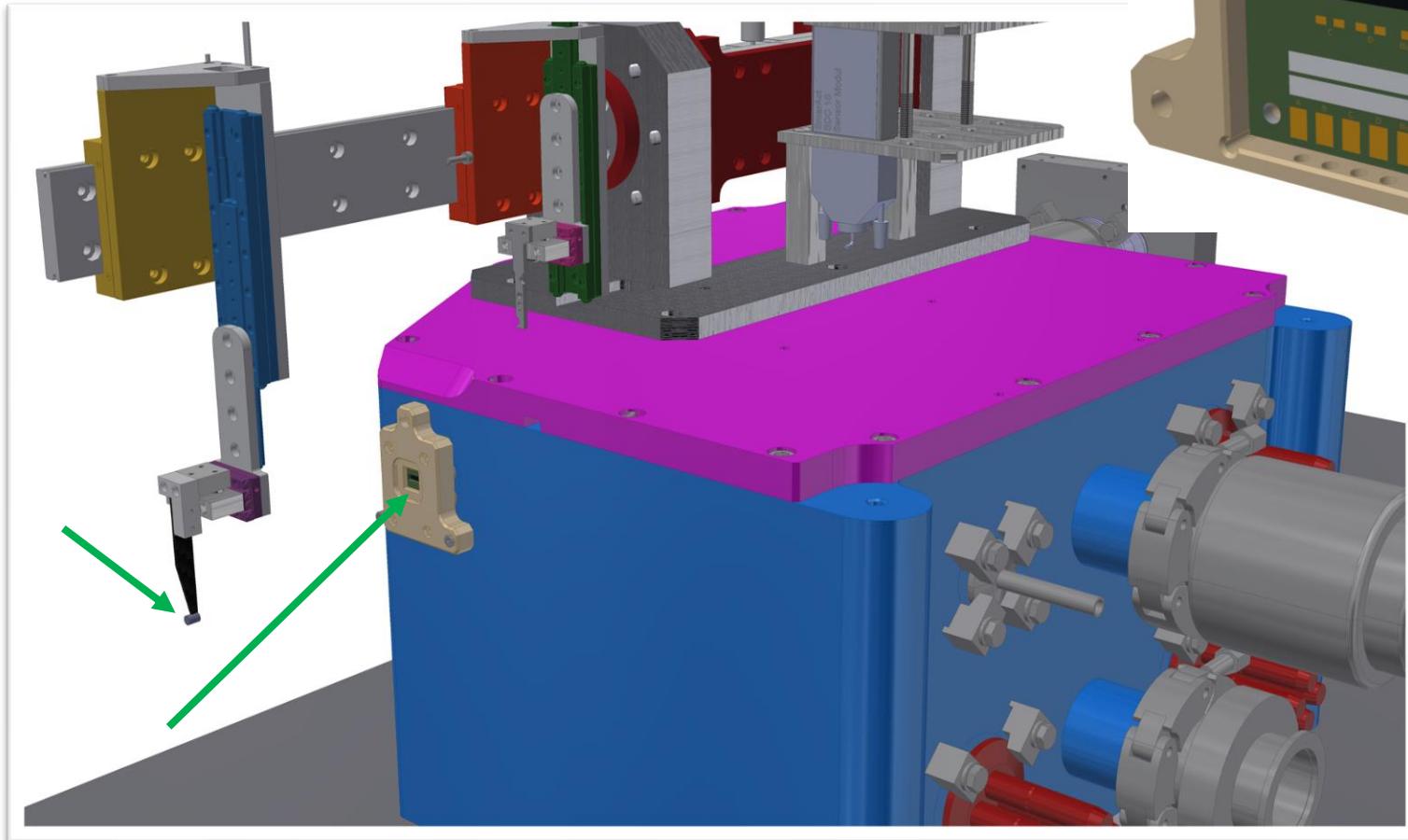




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Near sample monitoring

-Fast/compact intensity sensor*





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Near sample monitoring

- Fast/compact intensity sensor*





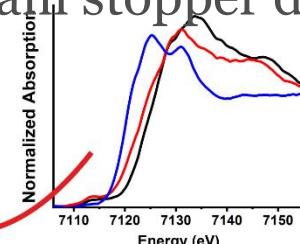
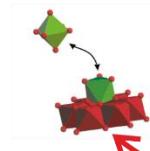
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SEnSiC^{CH}

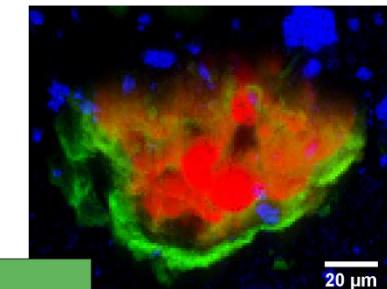
Near sample monitoring

- Beam stopper diode (no transmittance mode)



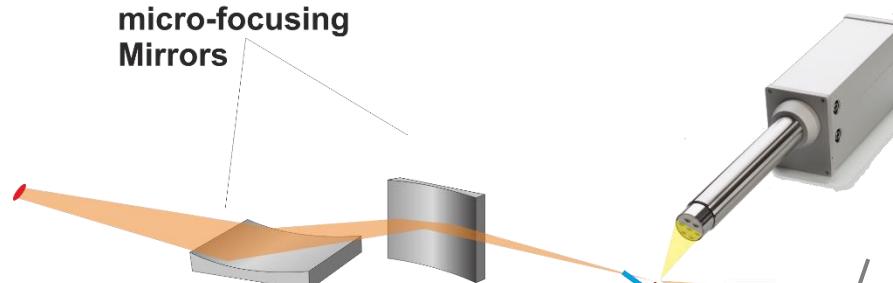
microscopic X-ray Absorption-Spectroscopies

- Oxidation state
- Chemical speciation
- Local atomic coordination



TI
Mn
Si

micro-focusing
Mirrors



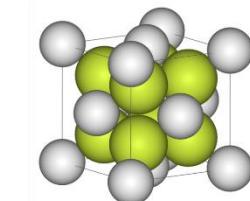
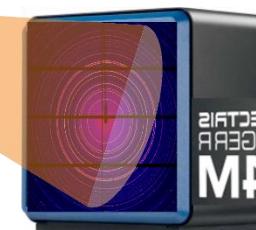
Spot-size
 $\gtrsim 1 \times 1 \mu\text{m}^2$

2D raster scan and
3D scanning tomography



XRF detector

- Local element stoichiometry/composition



XRD detector

- Crystalline phase identification
- Chemical speciation
- Stress



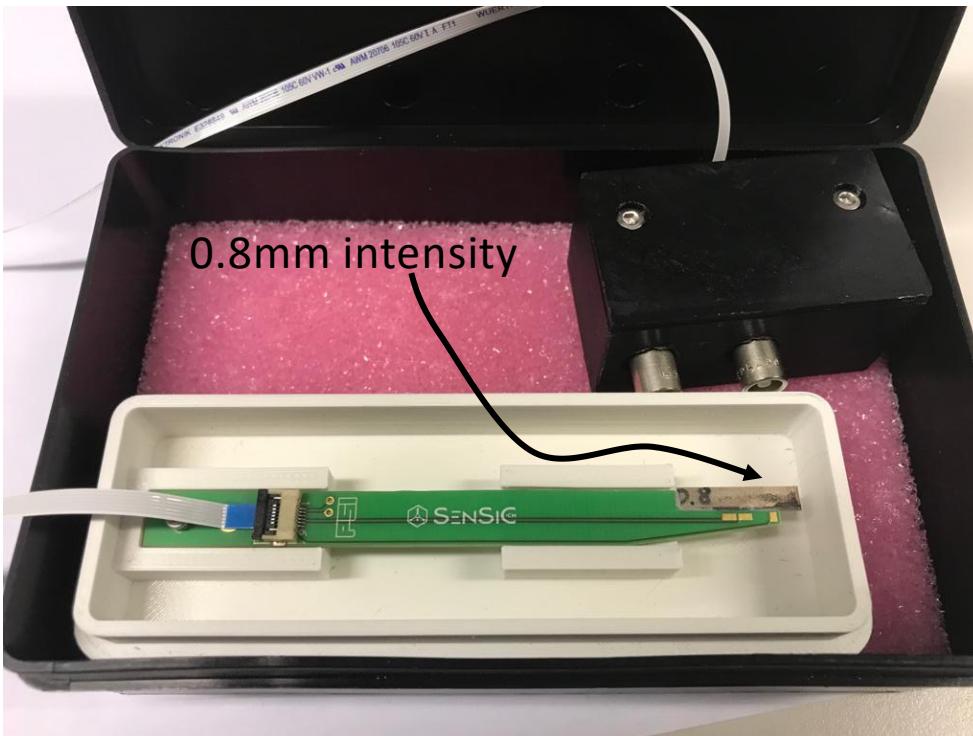


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Near sample monitoring

-Beam stopper diode (no transmittance mode)



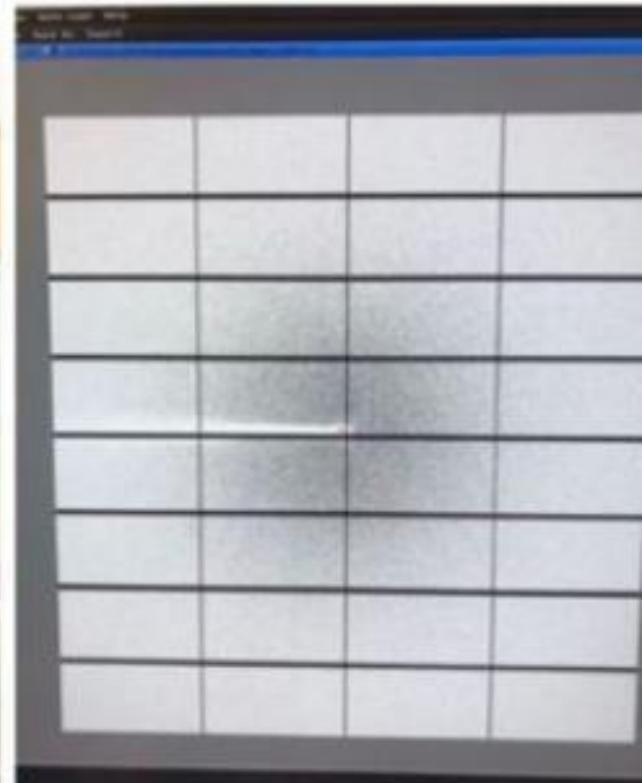
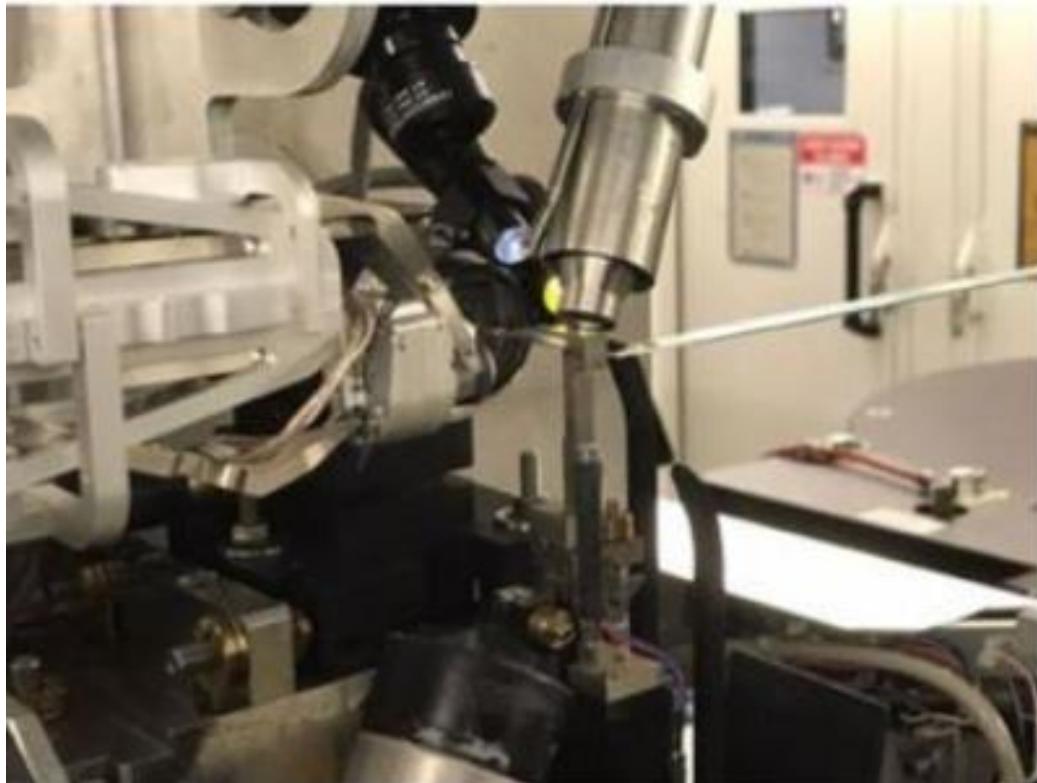
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Near sample monitoring

-Beam stopper diode (no transmittance mode)



*

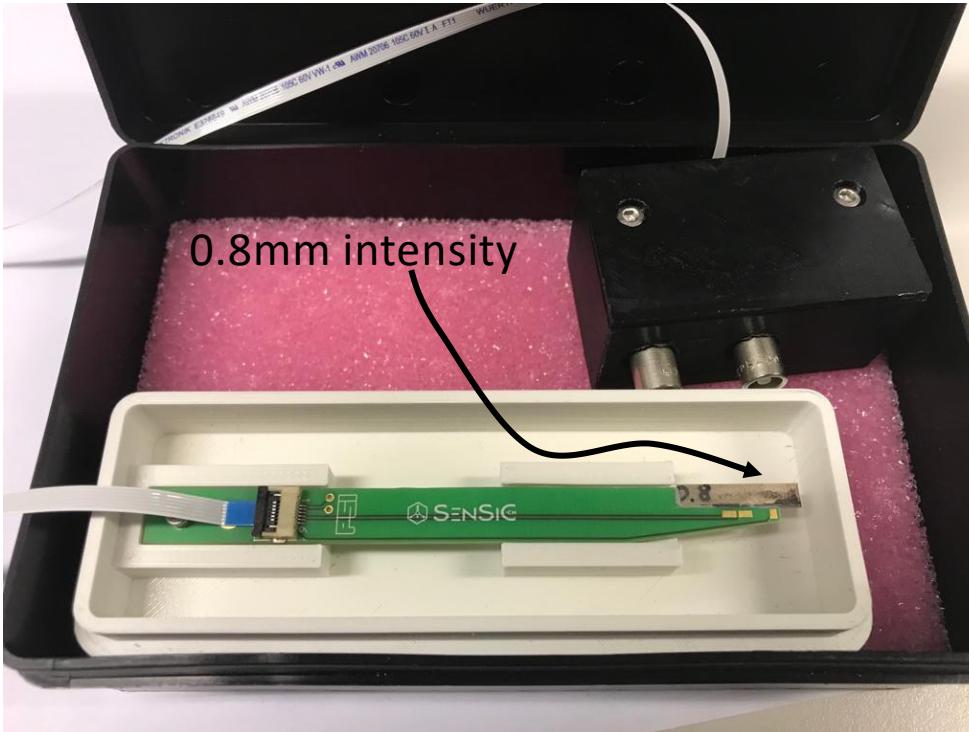
massimo.camarda@senSiC.ch



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Near sample monitoring

-Beam stopper diode (no transmittance mode)



- 0.8mm intensity monitor
- 2mm intensity monitor
- 2mm position monitor
- 3mm position monitor

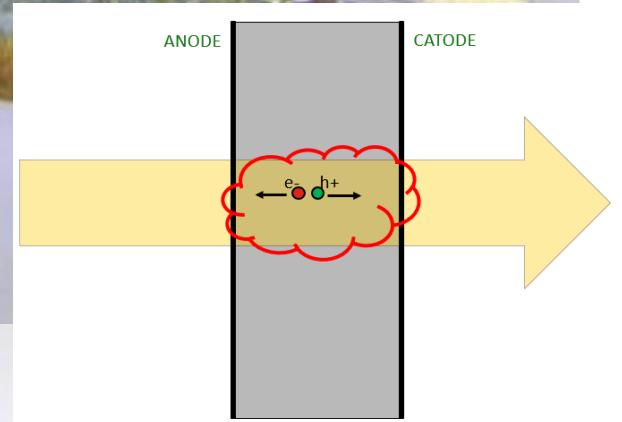
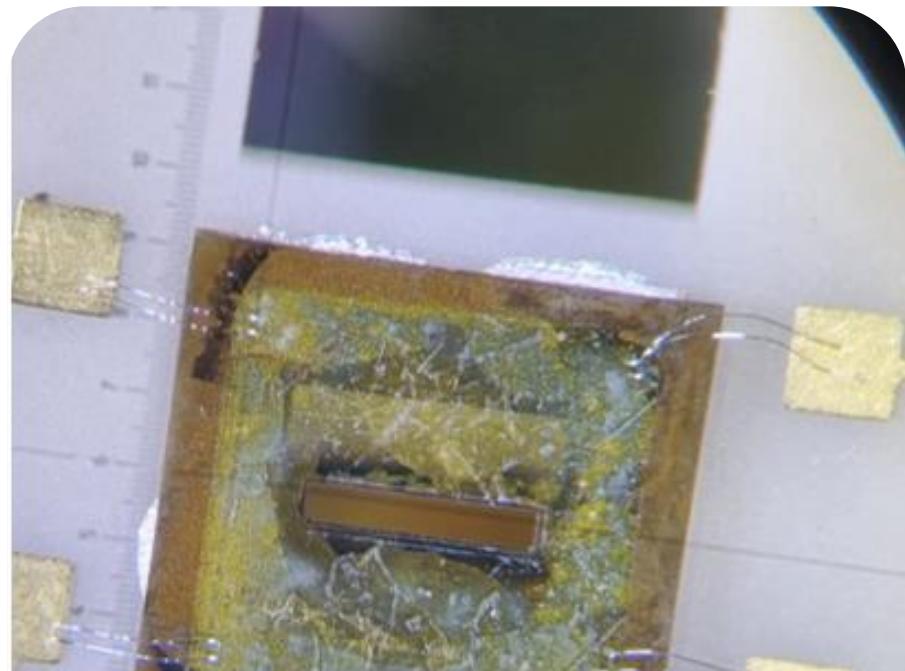
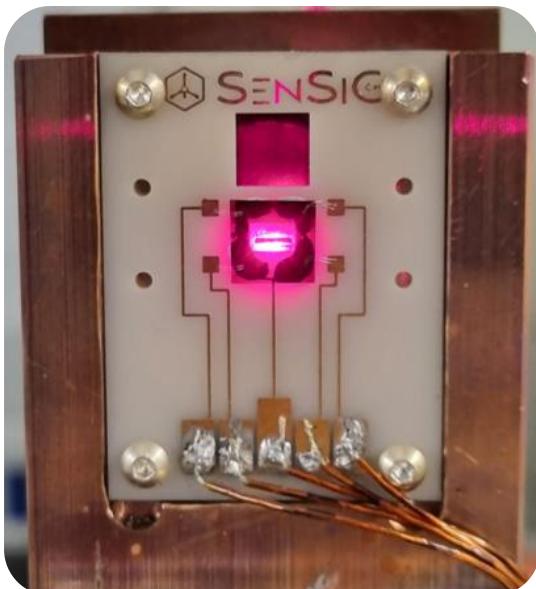


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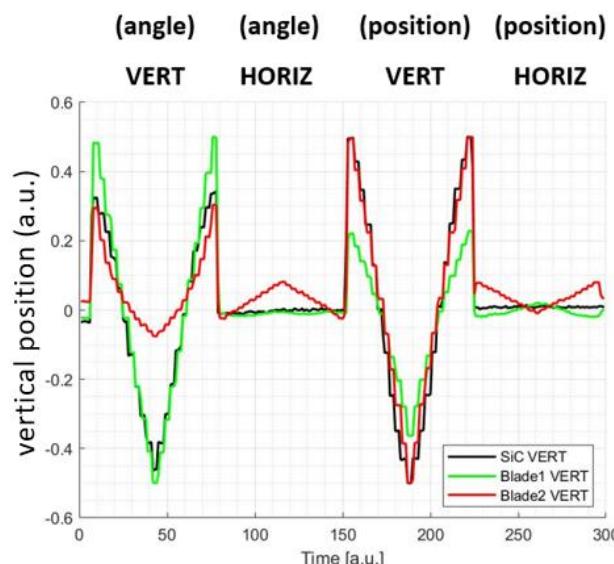
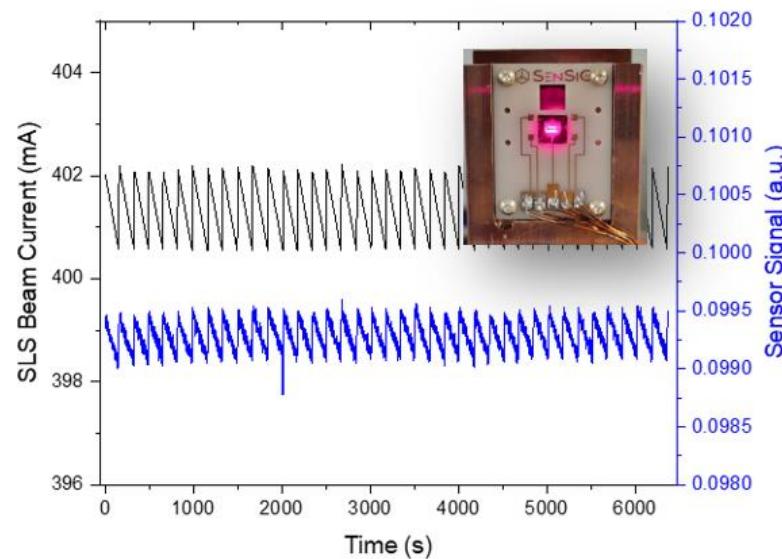
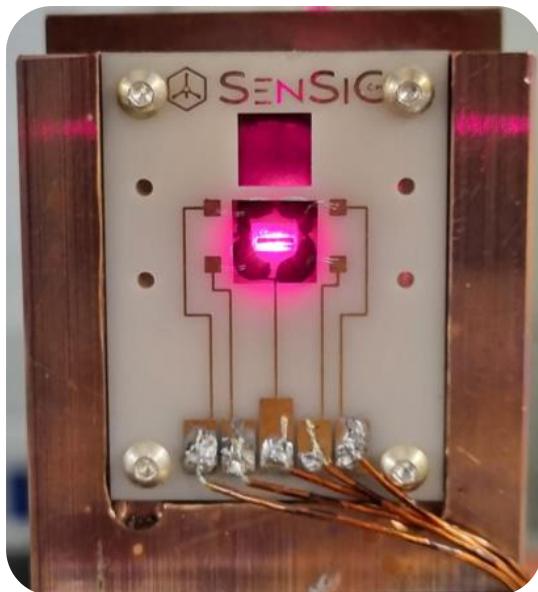
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POLYCHROMATIC MONITORING





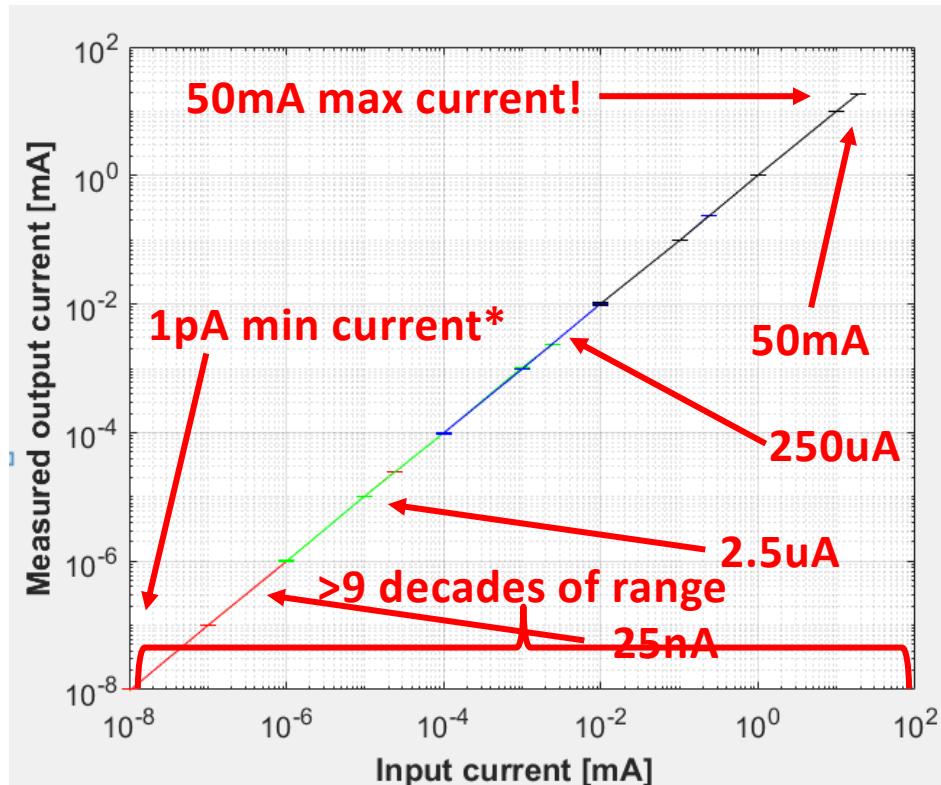
POLYCHROMATIC MONITORING





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NEW READOUT SYSTEM



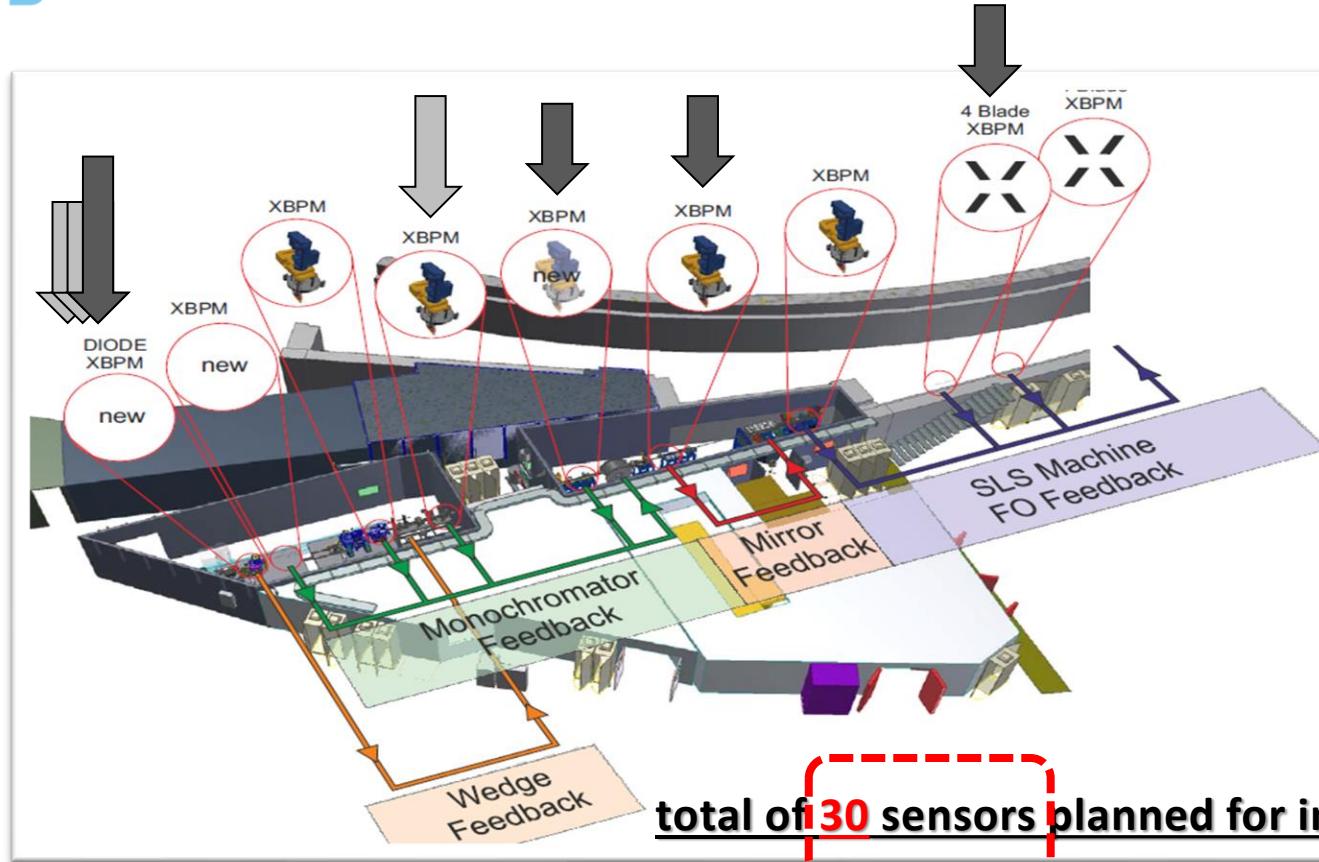
EPICS (QuadEM) COMPATIBLE, WITH POSSIBILITY OF
MUTIPLEXING AMONG SENSORS



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microXAS@PSI currently represents the most advanced “XBPM-monitored” beamline WW



- **Currently installed:**
n.7 sensors (after mono, I0, nano-focus, pinkbeam and beam-stopper intensity)
- **Planned:** multiple pixelated, before mono, whitebeam, beam-stopper position



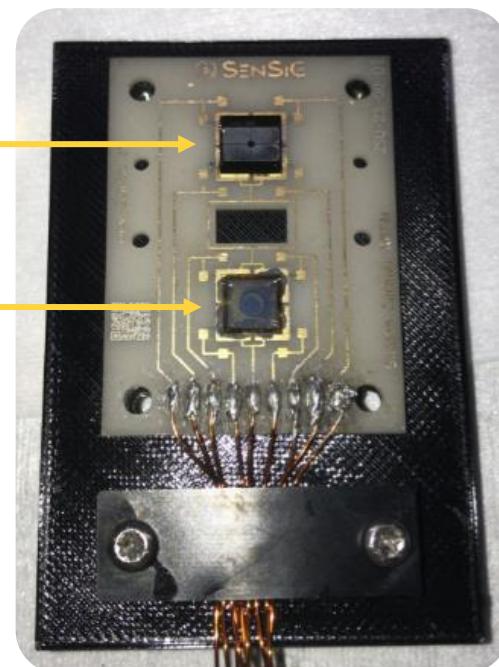
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Multi-sensors packaging



SENSOR FOR WHITE BEAM

SENSOR FOR MONOCHROMATIC BEAM

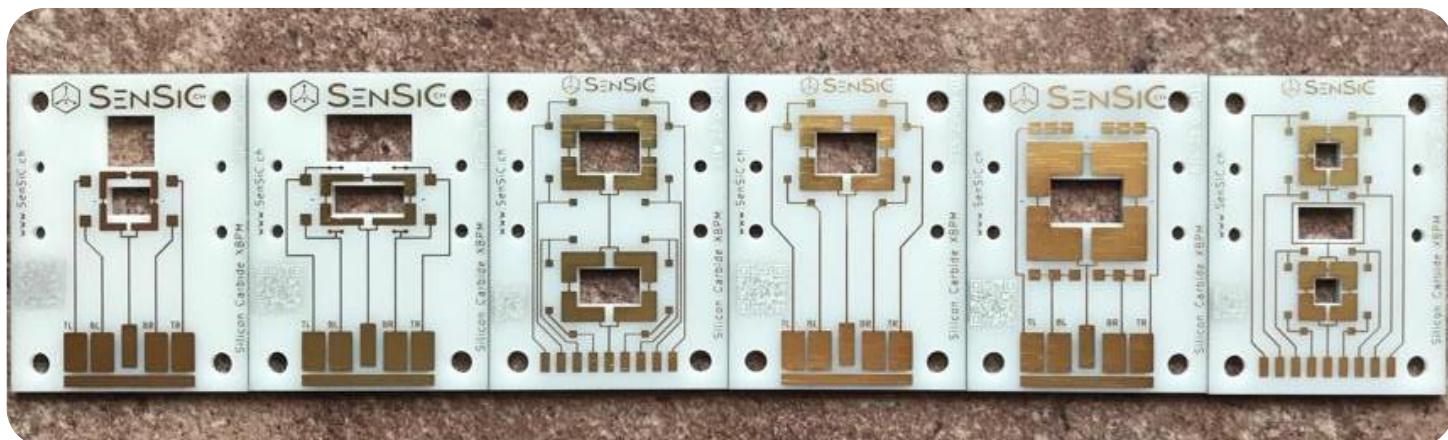
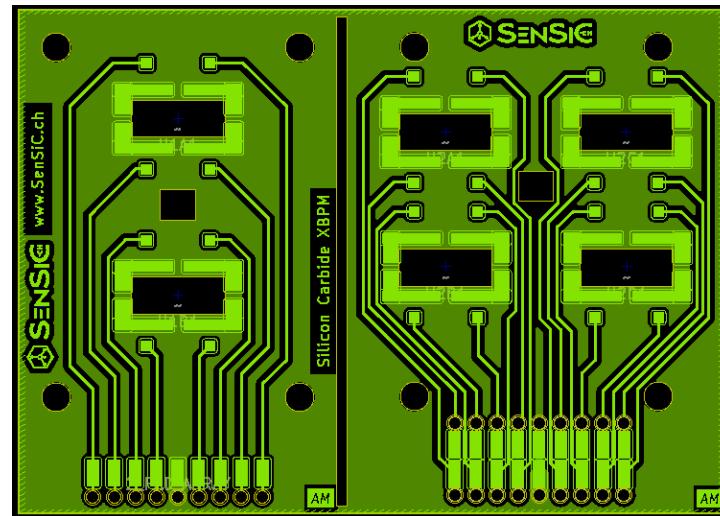




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Multi-sensors packaging





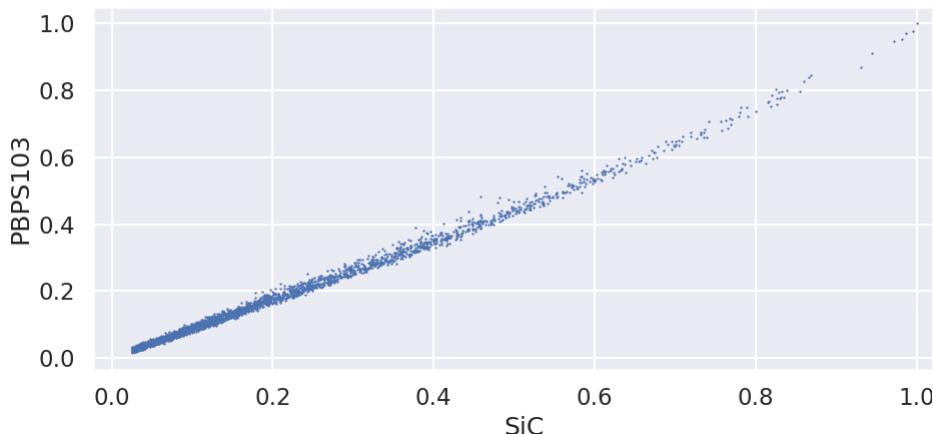
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FIRST LIGHT AT SwissFEL

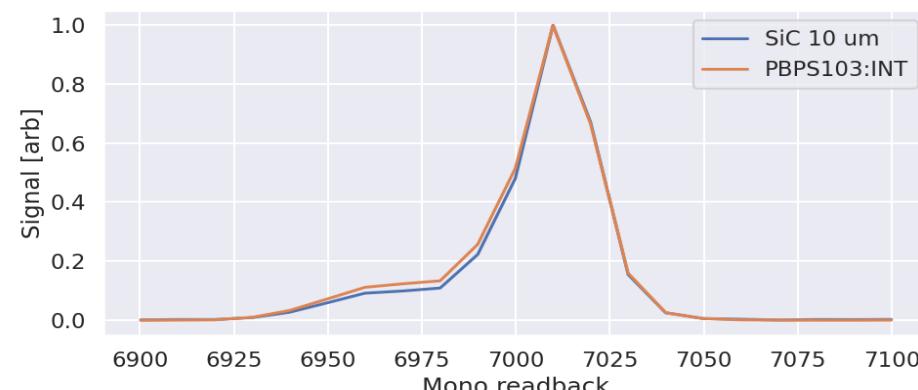


- 7 keV, PINKBEAM, 1 mJ/pulse

Correlation over mono scan



7 keV, 200 V bias



Huge signal level

- Needs attenuated mono beam
- 40 dB electrical signal attenuation (x100)
- Biasing increase from 40 - 200 V helps but nonlinearity observed



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CONCLUSIONS



SEnSiC
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- DEVELOPED INLINE MONITORS WITH GREATER POTENTIALITIES AND POSSIBILITIES THAN DIAMOND BASED ONES
- CONSOLIDATED PRODUCTS : MONOCHROMATIC, INTENSITY/POSITION, MONITORS 1.5um
- NEW PRODUCTS: POLYCHROMATIC, INTENSITY/POSITION, MONITORS
- NEW PRODUCTS: BEAMSTOPPERS, INTENSITY/POSITION, OF DIFFERENT SIZES (<0.8mm)
- NEW PRODUCTS: READOUT SYSTEMS (EPICS COMPATIBLE) WITH VERY LARGE DYNAMIC RANGES (UP TO 50mA)
- DEVELOPING MULTI-CHIP SENSORS (X2). (X3-X4 IN PROGRESS)
- FIRST PROMISING TEST AT XFEL

COLLABORATION WITH FMB-OXFORD

